MC33775A
14 cells battery cell controller IC

1 Product profile

1.1 General description

The MC33775A is a lithium-ion battery cell controller IC designed for automotive applications, such as hybrid electric vehicle (HEV) and electric vehicle (EV). It can be used in industrial applications, such as energy storage system (ESS) and uninterruptible power supply (UPS) systems. The device measures differential high precision cell voltages as well as temperatures. Additionally, the device provides an extensive set of passive cell voltage balancing features to equalize the individual cell voltages across the battery stack. The device offers serial peripheral interface (SPI) and an isolated daisy chain interface for communication with the host MCU. The MC33775A offers increased safety level and a low bill of materials.

1.2 Features and benefits

- AEC-Q100 grade 1 qualified: −40 °C to +125 °C ambient temperature range
- ISO 26262 ASIL D support for cell voltage, module voltage, and temperature measurements
- Cell voltage measurement
  - 4 to 14 cells per device
  - Supports bus bars with ±5 V input voltage
  - 16-bit resolution and ±1 mV typical measurement accuracy with ultra low long-term drift
  - 120 µs synchronicity of cell voltage measurements
  - Integrated configurable digital filter
- External temperature and auxiliary voltage measurements
  - Eight analog inputs
  - 5 V input range, configurable as absolute or ratiometric
  - 16-bit resolution and ±5 mV typical measurement accuracy
  - Integrated configurable digital filter
- Module voltage measurement
  - 9.6 V to 65 V input range
  - 16-bit resolution and 0.3 % measurement accuracy
  - Integrated configurable digital filter
- Internal measurement
  - Two redundant internal temperature sensors
  - Supply voltages
  - External transistor current
- Cell voltage balancing
  - 14 internal balancing field effect transistors (FETs), up to 300 mA per channel (max)
  - Simultaneous passive balancing of all channels
  - Global balancing timeout timer
  - Timer controlled balancing with individual timers with 10 s resolution and up to 45 h duration
  - Voltage controlled balancing with two thresholds to stop the affected cell or stop all balancing
  - Temperature controlled balancing; if balancing resistors are in overtemperature, balancing is interrupted

- – Pulse width modulation (PWM) controlled balancing
- – Balancing auto pause during measurement
- – Global pre-balancing delay
- – Automatic discharge of the battery pack (emergency discharge)
- I^2C-bus master interface to control external devices, for example, EEPROMs and security ICs
- Configurable alarm output
- Cyclic wake-up to supervise the pack during sleep and balancing
- Host interface supporting SPI or transformer physical layer 3 (TPL3)
  - – 2 Mbit data rate for TPL3 interface
  - – 4 Mbit data rate for SPI
- TPL3 communication supports
  - – Two-wire daisy chain with capacitive and inductive isolation
  - – Protocol supporting up to six daisy chains and 62 nodes per chain
- Unique device ID
- Operation modes
  - – Active mode
  - – Sleep mode
  - – Cyclic mode
  - – Deep sleep mode

2 Ordering information

Table 1. Ordering information

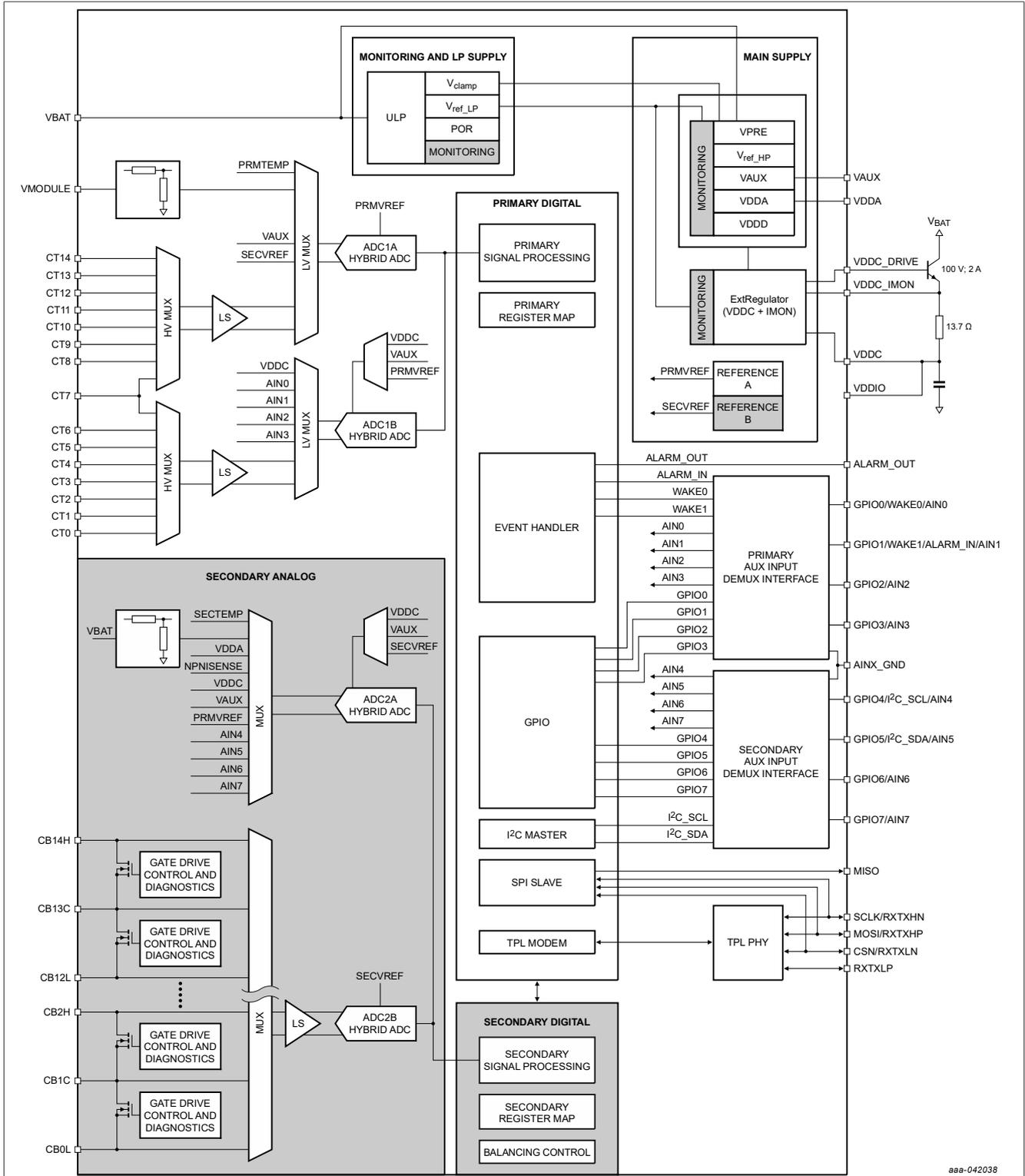| Type number	Package		
	Name	**Description**	**Version**
MC33775ATA1AE	LQFP64	plastic, thermal enhanced low profile quad flat package; 64 terminals; 0.50 mm pitch; 10 x 10 x 1.4 mm body	SOT1510-2

2.1 Ordering options

Table 2. Part numbers

Type number	Description
MC33775ATA1AE	TPL interface
Not available	SPI

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3   Block diagram

Figure 1 shows the general architecture of the MC33775A.

Figure 1. Block diagram

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4 Limiting values

4.1 Characteristics

Table 3. Limiting vales

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{BAT}	battery supply voltage		−0.3	-	+75	V
V_{module}	module voltage measurement input		−0.3	-	+75	V
$V_{I(CTn)}$	cell terminal input voltage	n = 0 to 14	−0.3	-	(n + 1) × 5	V
$V_{dif(CT)}$	cell terminal input differential voltage		−7	-	+10	V
$I_{I(CTn)}$	cell terminal input current	open load detection disabled	−500	-	+500	nA
$V_{bal(CTn)H}$	cell terminal balance voltage high input	n ≥ 2; n belongs to even numbers	−0.3	-	(n + 1) × 5	V
$V_{bal(CTn)C}$	cell terminal balance voltage common balancing	n ≥ 1; n belongs to odd numbers	−0.3	-	(n + 1) × 5	V
$V_{bal(CTn)L}$	cell terminal balance voltage low input	n ≥ 0; n belongs to even numbers	−0.3	-	(n + 2) × 5	V
$V_{I(dif)bal}$	balancing input differential voltage		−0.3	-	+10	V
$I_{I(bal)}$	input current on balancing pins		-	-	330	mA
V_{DDA}	analog supply voltage		−0.3	-	+3.1	V
V_{DDC}	digital supply voltage		−0.3	-	+5.8	V
V_{DDIO}	I/O supply voltage		−0.3	-	+5.8	V
V_{AUX}	auxiliary voltage		−0.3	-	+5.8	V
V_{GPIOn}	voltage on GPIO pins		−0.3	-	V_{VDDC} + 0.5	V
V_{ALARM_OUT}	ALARM_OUT voltage		−0.3	-	V_{VDDIO} + 0.5	V
$V_{bus(TPL)}$	voltage on TPL communication bus pins	relative to pin VSSC	−10	-	+10	V
V_{RESET}	voltage on RESET pin		−0.3	-	+6.5	V
$V_{I(IMON\_VDDC)}$	input voltage on IMON_VDDC pin		−0.3	-	+7	V
$V_{I(DRIVE\_VDDC)}$	input voltage on DRIVE_VDDC pin		−0.3	-	+7	V
Thermal maximum ratings						
T_j	junction temperature		−40	-	+165	°C
T_{stg}	storage temperature		−55	-	+150	°C

Table 3. Limiting vales...continued

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{reflow(peak)}$	peak reflow temperature	Pin soldering temperature limit is for 10 s maximum duration. Not designed for immersion soldering.	-	-	260	°C
ESD ratings						
V_{ESD1}	electrostatic discharge voltage	at any pin; human body model (HBM): according to AEC-Q100-002 (100 pF, 1.5 kΩ)	−2	-	+2	kV
V_{ESD2}	electrostatic discharge voltage	at pin VBAT, CTx, VMODULE, CBx, VDDIO, VDDC, VSSC, CSN_RXTXLN, RXTXLP, MOSI_RXTXHP, SCLK_RXTXHN, GPIOx, ALARM_OUT, VSSD, RESET, VAUX, VSSA, AINX_GND, GNDSUB, GNDFLAG; HBM: according to AEC-Q100-002 (100 pF, 1.5 kΩ)	−4	-	+4	kV
V_{ESD3}	electrostatic discharge voltage	at all pins; charged device model (CDM): according to AEC-Q100-011 (field induced charge; 4 pF)	−500	-	+500	V
V_{ESD4}	electrostatic discharge voltage	at corner pins; CDM: according to AEC-Q100-011 (field induced charge; 4 pF)	−750	-	+750	V
V_{ESD5}	electrostatic discharge voltage	at pin VBAT, CTx, VMODULE, CBx, VDDIO, VDDC, VSSC, CSN_RXTXLN, RXTXLP, MOSI_RXTXHP, SCLK_RXTXHN, GPIOx, ALARM_OUT, VSSD, RESET, VAUX, VSSA, AINX_GND, GNDSUB, GNDFLAG; according to IEC 61000-4-2, unpowered (150 pF, 300 Ω) with recommended ESD capacitors as in section application information	−8	-	+8	kV
V_{ESD6}	electrostatic discharge voltage	at pin VBAT, CTx, VMODULE, CBx, VDDIO, VDDC, VSSC, CSN_RXTXLN, RXTXLP, MOSI_RXTXHP, SCLK_RXTXHN, GPIOx, ALARM_OUT, VSSD, RESET, VAUX, VSSA,	−8	-	+8	kV

Table 3. Limiting vales...*continued*

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		AINX_GND, GNDSUB, GNDFLAG; according to ISO 10605:2009 (150 pF, 2 kΩ) powered and unpowered; with recommended ESD capacitors as in section application information				

5 Revision history

Table 4. Revision history

Document ID	Release date	Short data sheet status	Change notice	Supersedes
MC33775A_SDS v.2.1	20230717	Product short data sheet	-	MC33775A_SDS v.2
Modifications:	Table 1 and Table 2: changed			
MC33775A_SDS v.2	20230613	Product short data sheet	-	MC33775A_SDS v.1
MC33775A_SDS v.1	20220204	Preliminary short data sheet	-	-

6 Legal information

6.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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